

■ Soldering Conditions

1. Reflow Soldering

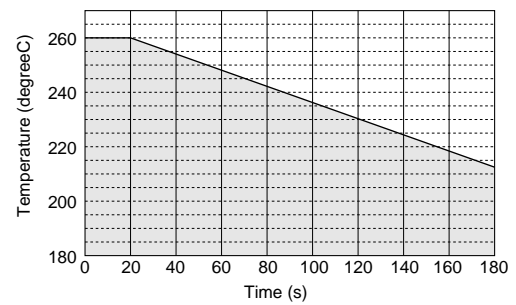
Soldering must be carried out without exceeding the allowable soldering temperature and time shown within the shaded area of FIGURE "Allowable Temperature and Time of Reflow Soldering". It is allowed to be reflow soldered up to twice with this condition. The standard soldering conditions are shown in FIGURE "Reflow Soldering Standard Conditions".

2. Hot Air Soldering

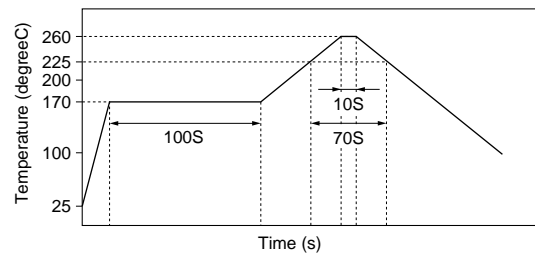
Hot air soldering should be carried out under the following conditions.

Pre-heating	Temperature	150°C
	Time	60 s to 120 s
Hot Air Soldering	Temperature	260±5°C, less than 5 s

Allowable Temperature and Time of Reflow Soldering



Reflow Soldering Standard Conditions



Measuring Point of Temperature : In-Out Terminals of Device
 Reflow Soldering : Both Convection and Infrared Rays
 : Hot Air